

Resin	Product Description	Tg (°C)	Z Axis Expansion (%)	UL-94 Rating	Td 5% (°C)	H ₂ O Absorp (%)	Tc (W/m-K)	IPC4101 Class	Comments
Polyimide Products									
33N	Flame Retardant Polyimide	250	1.2	V0	389	0.21	0.20	GIL /40 /41	Max Flame Retardance
35N	Flame Retardant Polyimide	250	1.2	V1	407	0.26	0.20	GIL /40 /41	Reduced Cure Time
HF-50	Powdered Poly Hole Fill Compound	250	0.55	n/a	>400	0.40	0.50	N/A	Hole/Via Fill Compound
84N	Filled Polyimide Prepreg	250	1.0	Meets HB	407	0.30	0.25	GIL /40 /41	For Via/Clearance Hole Filling
85N	High Temp Polyimide	250	1.2	HB	407	0.27	0.20	GIL /40 /41	Optimum Long Term Stability
85HP	High Performance Polyimide	>250	1.0	Meets HB	430	0.32	0.50	GIL /40 /41 /43	Tc (W/mK) is 2x Polyimide
84HP	Filled Polyimide Prepreg	>250	1.0	Meets HB	430	0.32	0.50	GIL /40 /41 /43	Fills Thick Copper Layers
<i>* PolyimideTg measured by Thermomechanical Analysis (TMA)</i>									
Low Flow Products									
37N	Low Flow Polyimide Prepreg	200	2.3	Meets V0	340	<1.00	0.30	GIJ /42	Rigid Flex Applications
38N	2nd Gen Low Flow Polyimide Prepreg	200	1.5	Meets V0	330	<1.00	0.30	GIJ /42	Enhanced Rheology Rigid Flex
47N	Modified Epoxy Low Flow	135	3.5	V0	315	0.10	0.25	GFG /21	Heat Sink Bond, Low Temp Cure
49N	Multifunctional Epoxy Low Flow	170	3.1	V0	303	0.10	0.25	GFG /26	Rigid-Flex, Heat Sinks
51N	Lead-Free Epoxy Low Flow	170	2.6	V0	368	0.15	0.25	GFG /126	Lead-Free Solderable, Rigid-Flex
Epoxy Products									
44N	Filled Epoxy Prepreg	170	2.2	V0	>300	0.10	0.30	GFG /98	For Via/Clearance Hole Fill
45N	Multifunctional Epoxy	175	2.4	V0	>300	0.10	0.25	GFG /26	High Layer Count MLBs
Controlled Thermal Expansion/SMT									
45NK	Woven Aramid Reinforced Epoxy	170	2.8	V0	>300	0.80	0.22	AFN /50	Kevlar® X-Y CTE of 5-7 ppm/°C
55NT	Epoxy Nonwoven Aramid	170	3.5	V0	368	0.30	0.20	BFG /55	X-Y CTE of 6-9 ppm/°C
85NT	Polyimide Nonwoven Aramid	250	2.3	Meets HB	426	0.60	0.20	BIL /53	X-Y CTE of 7-9 ppm/°C
85N/CIC	Polyimide Clad with CIC	250	1.5	HB	407	0.20	0.27	GIL /40 /41	CIC = Copper-Invar-Copper

Additional Product Information

- Reverse Treated and Double Treated Foils are available upon request
- Thin copper foils are available for ultra fine-line applications
- All products are manufactured using E-Type Fiberglass unless otherwise specified

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